Analog 4x1 Mux
Analog Super Buffer (ASB)
Output Channel Selector (ChanSel)
check_cap3_cell

pixel_cell

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check_cap3_cell

pixel_cell
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check_obus

[Diagram of circuit]
A Column of Pixel Cells (ColPixCell)

BOTTOM!!!
DAC Analog Mux 8-Ch. (DACAMUX_octal)
maskable 3:8 decoder (decoder8mask)
Inv
IO_pair

- InLeft
- Out

Components: R=240 Ohm, C=1 nF, T=200 Ohm, L=1 nH

Design Parameters:
- P: Parameter for power
- C: Decoupling capacitor
- L: Inductor
- R: Resistor
MOSIS TSMC 0.35um - Submicron Rules
Hi-ESD IO PAD SET

Input Pad with Buffer

Vdd Pad with ESD

Gnd Pad with ESD

Output Pad with Buffer

Analog IO Pad with ESD

Analog Reference Pad with ESD

Bidirectional Pad

PadNoConnect

p. 210

p. 210A
Rail-to-rail OTA
Output Select Column {OutSelCol}

BOTTOM!!!
Output Select Column (OutSelCol_top)

TOP!!!!
PADAREF

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Hi-ESD Bidirectional Pad
TSMC 0.35u MOSIS Technology

This pad can be used either for TFR export or for Spice export.
Bidirectional Pad

This module is the technology independent implementation of the Bidirectional Pad. It can be used for TPR, however it contains no information for exporting to Spice. In order to specify a technology for exporting to Spice, instance the appropriate PadBidirHE below.

For MOSIS 2.0 micron technology -
   PadBidirHE_2.0u
for MOSIS 1.2, 0.8, or 0.5 micron technologies -
   PadBidirHE_1.2u
Bonding Pad Inv
SCA Pass Transistor (sca_gate)
SCA Pass Transistor (big_passt)